Overview

HP Pro Mini 260 G9 Desktop PC



- 1. Type-C[®] SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
- 2. Type-A SuperSpeed USB 5Gbps signaling rate port
- 3. Type-A Hi-Speed USB 480Mbps signaling rate port (charge support up to 5V/1.5A)
 - **Not Shown**

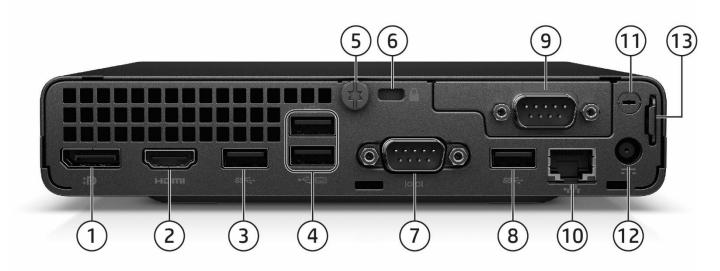
(2) M.2 (1 as M.2 2230 socket for WLAN/BT and 1 as M.2 2280 socket for storage)
(1) 2.5" internal storage drive bay

- 4. Combo Audio Jack with CTIA and OMTP headset support
- 5. Dual-state power button
- 6. Hard drive activity light



Overview

HP Pro Mini 260 G9 Desktop PC



- DisplayPort™ 1.4a (DP++)
- 2. HDMI 1.4b
- 3. Type-A SuperSpeed USB 5Gbps signaling rate port
- 4. Type-A Hi-Speed USB 480Mbs signaling rate port (2)
- 5. Cover release thumbscrew
- 6. Standard cable lock slot (10 mm)
- 7. Serial port

- 8. Type-A SuperSpeed USB 5Gbps signaling rate port
- 9. Flex Port 2¹, choice of:
 - Serial
 - 2nd External Antenna
- 10. RJ45 Network connector
- 11. External WLAN antenna opening
- 12. Power connector
- 13. Retractable Padlock loop

1. Must be configured at time of purchase

At A Glance

- 12th Generation Intel® processors (up to Core™ i5), featuring integrated Intel® UHD Graphics
- Choice of Windows 11 Professional, Windows 11 Home, and FreeDOS Up to 64GB of DDR4 Synchronous Dynamic Random Access Memory (SDRAM)
- Optional M.2 PCIe NVMe solid state drives (SSD) enabling faster system startup and application launches
- Support for up to two monitors via one standard HDMI 1.4b and one standard Display Port 1.4a.
- Serial port support comes standard, with ability to configure one additional for a total of two, enabling support for legacy peripherals
- Integrated 10/100/1000 Ethernet Controller
- Optional Wi-Fi 6E, Wi-Fi 6 and Wi-Fi 5 (802.11ac) connectivity
- Trusted Platform Module (TPM) 2.0
- VESA mounting incorporated into chassis design
- Dust filter available
- High efficiency energy saving power supply
- PC chassis and all internal components and modules are manufactured with low halogen content
- Protected by HP Services, including limited warranties up to 1-1-1(terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Compliance with CE (Class B) / FCC (Class B) / UL (UL60950-1 / UL62368-1) / CSA (CSA C22.2 No.60950-1-07 / CSA C22.2 No. 62368-1-14) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B)

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Standard Features and Configurable Modules

OPERATING SYSTEMS

Preinstalled Windows 11 Pro¹

Windows 11 Pro Education¹

Windows 11 Home - HP recommends Windows 11 Pro for business1

Windows 11 Home Single Language - HP recommends Windows 11 Pro for business¹

Windows 10 Pro (available through downgrade rights from Windows 11 Pro)¹

Windows 11 Pro (Windows 11 Enterprise or Windows 10 Enterprise available with a Volume

Licensing Agreement)1,2

FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

NOTE: In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

PROCESSORS

Intel® 12th Generation Core™ Processors

Intel® Core™ i5-1235U Processor¹
15W
1.3GHz base frequency
Up to 4.4 GHz max. Turbo frequency with Intel® Turbo Boost Technology²
12MB cache, 10 cores, 12 threads
Intel® Iris® Xe Graphics

Intel® Core™ i3-1215U Processor¹
15W
1.2GHz base frequency
Up to 4.4 GHz max. Turbo frequency with Intel® Turbo Boost Technology²
10MB cache, 6 cores, 8 threads
Intel® UHD Graphics

Intel® Pentium® Processors

Intel® Pentium® Gold 8505 Processor¹
15W
1.2 GHz base frequency
Up to 4.4 GHz max. Turbo frequency with Intel® Turbo Boost Technology²
8MB cache, 5 cores, 6 threads
Intel® UHD Graphics

Intel® Celeron® Processors

Intel® Celeron® 7305 Processor¹ 15W 1.1 GHz base frequency 8MB cache, 5 cores, 6 threads Intel® UHD Graphics

1. Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and



Standard Features and Configurable Modules

software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

2. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

GRAPHICS

Integrated

Intel® UHD Graphics, Intel® Iris® Xe Graphics1

NOTE: Intel[®] integrated UHD Graphics varies by processor 1: Intel[®] Iris[®] X^e Graphics¹ only support on Intel[®] Core[™] i5-1245U, i5-1235U

STORAGE

NOTE: Starting from November 1st 2023, all shipments will require Windows to be installed on SSD to provide users a better experience. HDD can only be configured as additional data drives and not the boot drive.

2.5 inch SATA Hard Disk Drives (HDD)

500GB* 7200RPM 2.5in SATA HDD 1TB* 7200RPM 2.5in SATA HDD 1TB* 5400RPM 2.5in SATA HDD 2TB* 5400RPM 2.5in SATA HDD

M.2 PCIe NMVe Solid State Drives (SSD)

256GB* M.2 2280 PCIe NVMe SSD 512GB* M.2 2280 PCIe NVMe SSD 1TB* M.2 2280 PCIe NVMe SSD

256GB* M.2 2280 PCIe NVMe Three Layer Cell SSD

512GB* M.2 2280 PCIe NVMe Three Layer Cell SSD

1TB* M.2 2280 PCIe NVMe Three Layer Cell SSD

2TB* M.2 2280 PCIe NVMe Three Layer Cell SSD

256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD**

512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD**

*NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

**NOTE: Storage DriveLock does not work with Self Encrypting or Optane based storage.



Standard Features and Configurable Modules

MEMORY

Type

DDR4-3200(Transfer rates up to 3200MT/s)

Maximum

64GB capacity

Memory Configurations

2 SODIMMs

4GB (4GB x 1)

8GB (4GB x 2)

8GB (8GB x 1)

16GB (8GB x 2)1

16GB (16GB x 1)

32GB (16GB x 2)1

32GB (32GB x 1)

64GB (32GB x 2)

1. For Dual channel memory, due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.

NOTE: Memory modules support data transfer rates up to 3200 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.

NOTE: All memory slots are customer accessible / upgradeable.

NETWORKING/COMMUNICATIONS

Networking

Intel® I219-V Gigabit Network Connection LOM (Non-vPro)

Wireless

Realtek RTL8821CE Wi-Fi 51 (802.11ac) 1x1 with Bluetooth® 4.2 Wireless Card M.2

Intel® Wi-Fi 6E² AX211 802.11ax 2x2 with Bluetooth® 5.3 Wireless Card M.2 non-vPro™

Realtek 8852BE Wi-Fi 6 with Bluetooth® 5.3 Wireless Card M.2

- 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.
- 2. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.
- 3. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs

KEYBOARDS/POINTING DEVICES

Keyboard

HP 125 Wired Keyboard

HP USB Business Slim Wired SmartCard CCID Keyboard

Mouse

HP Wired Desktop 320M Mouse



Standard Features and Configurable Modules

HP Wired 125 Mouse HP Wired 128 Laser Mouse

NOTE: Availability may vary by country



Standard Features and Configurable Modules

SECURITY

TPM 2.0¹ (FW: 15.23) endpoint security controller (Infineon SLB9672). Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified.

Intrusion Sensor (integrated in the system board, can be enabled/disabled through BIOS)

Support for chassis cable lock devices

Support for chassis padlocks devices

SATA port disablement (via BIOS)

Serial, USB enable/disable (via BIOS)

Removable media write/boot control

Power-on password (via BIOS)

Setup password (via BIOS)

1. In some scenarios, machines pre-configured with Windows OS might ship with TPM turned off

PORTS

Internal slots and Ports

- (1) M.2 PCIe x1 2230 (for WLAN)
- (1) M.2 PCIe x4 2280 (for storage)
- (1) Integrated SATA storage connector

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

Bays

2.5" Internal Storage Drive

Standard User Accessible Ports

Front (1) Type-C[®] SuperSpeed USB 10Gbps signaling rate port

(1) Type-A Hi-Speed USB 480Mbps signaling rate port

(1) Type-A SuperSpeed USB 5Gbps signaling rate port

(1) Combo Audio Jack with CTIA and OMTP headset support

Rear (2) Type-A SuperSpeed USB 5Gbps signaling rate port

(2) Type-A Hi-Speed USB 480Mbps signaling rate port

(1) Display Port 1.4a

(1) HDMI 1.4b

(1) RJ45

(1) Serial (RS-232)

Configurable Non-PCIe/PCI Slot User Accessible Ports

Rear Flexible Port, choice of Serial (RS-232), 2nd External antenna



Standard Features and Configurable Modules

USB SPECIFICATION AND MARKETING NAME MAPPING TABLE

Marketing Name	Technical Terminology
Hi-Speed USB 480Mbps signaling rate	USB 2.0
SuperSpeed USB 5Gbps signaling rate	USB 3.2 Gen 1
SuperSpeed USB 10Gbps signaling rate	USB 3.2 Gen 2
SuperSpeed USB 20Gbps signaling rate	USB 3.2 Gen 2x2



Standard Features and Configurable Modules

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP Desktop Support Utilities myHP HP Notifications HP Support Assistant¹ HP QuickDrop³ HP Smart Support⁴ Buy Office (Sold separately)

Manageability Features

HP Cloud Recovery²

Client Security Software

McAfee LiveSafe™ (1 year subscription)⁵

- 1. HP Support Assistant requires Windows and Internet access.
- 2. HP Cloud Recovery is available for select HP desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630.
- 3. HP Quick Drop requires Internet access and Windows 10 or higher PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.
- 4. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.
- 5 Availability may vary by country. McAfee LiveSafe 30-day free trial offer (Internet access required. First 30 days included. Subscription required for live updates afterwards.)



Standard Features and Configurable Modules

UNIT ENVIRONMENT AND OPERATING CONDITIONS

ENERGY STAR® certified models available

ENERGY STAR® certified. EPEAT® registered where applicable. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.

Low halogen (chassis, all internal components and modules)¹

TAA compliant models available

1. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's recirculated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 50° to 95° F (10° to 35° C)²

Non-operating: -22° to 140° F(-30° to 60° C)

Relative Humidity Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 0% to 95% (non-condensing at ambient)

Maximum Altitude (unpressurized)Operating:10,000 ft (3048 m)

Non-operating: 30,000 ft (9144 m)

2. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.



Standard Features and Configurable Modules

ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations	This product has received or is in be labeled with one or more of the IT ECO declaration US ENERGY STAR® US Federal Energy Mana EPEAT® Gold registered is status in your country. TCO Certified China Energy Conservati China State Environmen Taiwan Green Mark Korea Eco-label Japan PC Green label Commission Regulation	nese marks: ngement Program in the United Stat ion Program (CEC tal Protection Ad	n (FEMP) res. See http://wv rP) ministration (SEF	ww.epeat.net for registration
System Configuration		The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC	C, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	4.9000 W	5.010	00 W	4.7000 W
Normal Operation (Long idle)	1.3700 W	1.450	00 W	1.2100 W
Sleep	1.3500 W	1.430	00 W	1.1900 W
Off	0.5000 W	0.520	00 W	0.4600 W
	PC featuring a hard disk drive, a high	he ENERGY STAR® L PA) ENERGY STAR® nfigurations, then o efficiency power s	ogo are certified w specifications for c energy efficiency d upply, and a Micros	vith the applicable U.S. computers. If a model family does ata listed is for a typically configured soft Windows® operating system.
Heat Dissipation*	115VAC, 60Hz	230VAC	., 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	16.7090 BTU/hr	17.0841	BTU/hr	16.0270 BTU/hr
Normal Operation (Long idle)	4.6717 BTU/hr	4.9445		4.1261 BTU/hr
Sleep	4.6035 BTU/hr	4.8763		4.0579 BTU/hr
Off	1.7050 BTU/hr	1.7732	BTU/hr	1.5686 BTU/hr
	NOTE: Heat dissipation is calculated one hour.	based on the meas	ured watts, assum	ing the service level is attained for
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)			Sound Pressure (L _{PAm} , decibels)
Typically Configured – Idle	2.7			17
Fixed Disk – Random writes	2.9			17



Standard Features and Configurable Modules

Longevity and Upgrading		can be upgraded, possibly extending its useful life b l/or components contained in the product may includ	
		memory slots eable M.2 PCIe NVME SSD & 2.5" SATA HDD	
	Spare parts a production.	are available throughout the warranty period and or	for up to 5 years after the end of
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product contains 0% post-consumer recycled plastic (by wt.) This product is 95.1% recycle-able when properly disposed of at end of life. 		
Dackasina Materiala	External:	DADED/Corrugated	450.0
Packaging Materials	External:	PAPER/Corrugated PAPER/Molded Pulp	450 g
	Internal:	PLASTIC/Polyethylene low density - LDPE	74 g
			5 g
		packaging material contains at least 30% recycled co Ited paper packaging materials contains at least 35%	
Material Usage	to the HP Ge	does not contain any of the following substances in neral Specification for the Environment at hp.com/hpinfo/globalcitizenship/environment/pdf/g	
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.		



Standard Features and Configurable Modules

	 Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	 Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in
	packaging materials.
	 Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	 Design packaging materials for ease of disassembly.
	 Maximize the use of post-consumer recycled content materials in packaging materials.
	 Use readily recyclable packaging materials such as paper and corrugated materials.
	 Reduce size and weight of packages to improve transportation fuel efficiency.
	 Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
	HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for
	each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers.
	These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM
HP Inc.	customers who integrate and re-sell HP equipment. For more information about HP's commitment to the environment:
Corporate	For more imprination about he 5 commitment to the environment.
Environmental	Global Citizenship Report
Information	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K _Certificate.pdf
	certificate.pdf and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SERVICE AND SUPPORT

On-site Warranty¹: Three-year (3-3-3) or one-year (1-1-1) limited warranty delivers three years or one year of on-site, next business day² service for parts and labor and includes free support 24 x 7³. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.⁴

- 1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 2. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
- 3. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 4. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications – Graphics

GRAPHICS

Intel® UHD Graphics (integrated)¹

Graphics Controller Integrated

HDMI Supports HDMI 1.4b features

Supports HDCP 2.2

Supports audio over HDMI

DisplayPort Supports DisplayPort 1.4a

Memory The actual amount of maximum graphics memory can be >4GB. System memory is allocated for

graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an

optimal balance between graphics and system memory use.

Maximum Color Depth up to 10 bits/color
Graphics/Video API Support HEVC 10b Enc/Dec HW

VP9 10b Dec HW

HDR Rec. 2020 DX12

 Max. Resolution (VGA)
 2048 x 1536@60Hz

 Max. Resolution (HDMI)
 4096 x 2160@60Hz



Technical Specifications – Storage

STORAGE

NOTE: Starting from November 1st 2023, all shipments will require Windows to be installed on SSD to provide users a better experience. HDD can only be configured as additional data drives and not the boot drive.

500GB 7200RPM 2.5in SATA HDD

Capacity500GBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer SizeUp to 128MBLogical Blocks976,773,168Seek Time12 ms (Average)

 Height
 0.283in/7.2mm (Max)

 Width
 2.75in/70mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

1TB 7200RPM 2.5in SATA HDD

Capacity 1TB

Rotational Speed 7,200 rpm
Interface SATA 6 Gb/s
Buffer Size Up to 128MB
Logical Blocks 1,953,525,168
Seek Time 12 ms (Average)

 Height
 0.283in/7.2 mm (Max)

 Width
 2.75in/70mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

1TB 5400RPM 2.5in SATA HDD

Capacity 1TB

Rotational Speed 5,400 rpm
Interface SATA 6 Gb/s
Buffer Size Up to 128MB
Logical Blocks 1,953,525,168
Seek Time 12ms (Average)

 Height
 0.283in/7.2mm (Max.)

 Width
 2.75in/70mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)



HP Pro Mini 260 G9 Desktop PC

QuickSpecs

Technical Specifications – Storage

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.



Technical Specifications – Storage

2TB 5400RPM 2.5in SATA HDD

Capacity 2TB

Rotational Speed 5,400 rpm **Interface** SATA 6 Gb/s **Buffer Size** 128MB

 Logical Blocks
 3,907,050,336

 Seek Time
 12 ms (Average)

 Height
 0.374in/9.5mm (Max.)

 Width (nominal)
 2.75in/70mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10a 256GB Capacity Height 2.3 mm Length 80 mm Width 22 mm Interface PCIe NVMe **Maximum Sequential Read** 3200MB/s ±20% **Maximum Sequential Write** 2000MB/s ±20% **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

512GB M.2 2280 PCIe NVMe SSD

Drive Weight< 10g</th>Capacity512GBHeight2.3 mmLength80 mmWidth22 mmInterfacePCIe NVMe

Maximum Sequential Read3200MB/s ±20%Maximum Sequential Write3200MB/s ±20%Logical Blocks1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM: L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.



Technical Specifications – Storage

1TB M.2 2280 PCIe NVMe SSD

Drive Weight< 10g</th>Capacity1TBHeight2.3 mmLength80 mmWidth22 mmInterfacePCIe NVMe

Maximum Sequential Read3200MB/s ±20%Maximum Sequential Write3200MB/s ±20%Logical Blocks2,000,409,264

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10q Capacity 256GB Height 2.3 mm Length 80 mm Width 22 mm **Interface** PCIE Gen4x4 **Maximum Sequential Read** 4000MB/s ±20% **Maximum Sequential Write** 2000MB/s ±20% **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2; Pyrite 2.0

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10q Capacity 512GB Height 2.3 mm Length 80 mm Width 22 mm Interface PCIE Gen4x4 **Maximum Sequential Read** 6400MB/s ±20% **Maximum Sequential Write** 3500MB/s ±20% **Logical Blocks** 1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2; Pyrite 2.0



Technical Specifications – Storage

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

1TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10q Capacity 1TB Height 2.3 mm Length 80 mm Width 22 mm Interface PCIE Gen4x4 **Maximum Sequential Read** 6400MB/s ±20% **Maximum Sequential Write** 5000MB/s ±20% **Logical Blocks** 2,000,409,264

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2; Pyrite 2.0

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

2TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10q Capacity 2TB Height 2.3 mm Length 80 mm Width 22 mm Interface PCIE Gen4x4 **Maximum Sequential Read** 6400MB/s ±20% **Maximum Sequential Write** 5000MB/s ±20% **Logical Blocks** 4,000,797,360

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2; Pyrite 2.0

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.



Technical Specifications – Storage

256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight < 10q Capacity 256GB Height 2.3 mm Length 80 mm Width 22 mm Interface PCIE Gen4x4 **Maximum Sequential Read** 4000MB/s ±20% **Maximum Sequential Write** 2000MB/s ±20% **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2; TCG Opal 2.0

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight < 10q Capacity 512GB Height 2.3 mm 80 mm Length Width 22 mm Interface PCIE Gen4x4 **Maximum Sequential Read** 6400MB/s ±20% **Maximum Sequential Write** 3500MB/s ±20% **Logical Blocks** 1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2; TCG Opal 2.0

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.



Technical Specifications – Networking

NETWORKING AND COMMUNICATIONS

	letwork Connection LOM (non-vPro)
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
	100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
	1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40)
	Auto-Negotiation (Automatic Speed Selection)
	Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support
	IEEE 802.1q VLAN support
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)
	IEEE 802.3az EEE (Energy Efficient Ethernet)
	IEEE 802.3i 10BASE-T
	IEEE 802.3u 100BASE-TX
	IEEE 802.3ab 1000BAE-T
	IEEE 802.3bz 2.5GBASE-T
Performance	TCP/IP/UDP Checksum Offload (configurable)
	Protocol Offload (ARP & NS)
	Large send offload and Giant send offload
	Receiving Side Scaling (Hash Mode only)
	Jumbo Frame 9K
Power consumption	Cable Disconnetion: 25mW
	100Mbps Full Run: 450mW
	1000bp Full Run: 1000mW
	WoL Enable(S3/S4/S5): 50mW
	WoL Disable(S3/S4/S5): 25mW
Power	ACPI compliant – multiple power modes
Management	Situation-sensitive features reduce power consumption
	Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame);
	Wake-on-LAN from off (Magic Packet only)
	PXE 2.1 Remote Boot
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))
	Comprehensive diagnostic and configuration software suite
	Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® non vPro™ support with appropriate Intel® chipset components



Intel AX211 Wi-Fi 6E +BT 5.3	B Wireless Card M.2 160MHz CNVi WW WLAN ¹
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi [®] certified
Frequency Band	802.11b/g/n/ax
	• 2.402 – 2.482 GHz
	802.11a/n/ac/ax
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
	• 5.955 – 6.415 GHz
	• 6.435 – 6.515 GHz
	• 6.535 – 6.875 GHz
	• 6.895 – 7.115 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
Data Kates	
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: max 300Mbps
	• 802.11ac: 1733Mbps
	• 802.11ax: max 2.4Gbps
Modulation	Direct Sequence Spread Spectrum
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	,1024QAM
Security ²	• IEEE and Wi-Fi® compliant 64 / 128 bit WEP encryption for a/b/g mode only
	AES-CCMP: 128 bit in hardware
	802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	WPA3 certification
	• IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	The first to receiv
	Infrastructure (Access Point Required)
Roaming	
Autout Dowers	IEEE 802.11 compliant roaming between access points
Output Power ³	• 802.11b: +17dBm minimum
	• 802.11g: +16dBm minimum
	• 802.11a: +17dBm minimum
	• 802.11n HT20(2.4GHz): +14dBm minimum
	• 802.11n HT40(2.4GHz): +13dBm minimum



	• 802.11n HT20(5GHz): +14dBm minimum
	• 802.11n HT40(5GHz): +13dBm minimum
	• 802.11ac VHT80(5GHz): +10dBm minimum
	• 802.11ac VHT160(5GHz): +10dBm minimum
	• 802.11ax HE40(2.4GHz): +12dBm minimum
	• 802.11ax HE80(5GHz): +10dBm minimum
	• 802.11ax HE160(5GHz): +10dBm minimum
Power Consumption	Transmit mode 2.0 W
•	Receive mode 1.6 W
	Idle mode (PSP) 180 mW (WLAN Associated)
	Idle mode 50 mW (WLAN unassociated)
	Connected Standby 10mW
	Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management
	802.11 compliant power saving mode
Receiver Sensitivity ⁴	•802.11b, 1Mbps: -93.5dBm maximum
neceiver sensitivity	•802.11b, 11Mbps: -84dBm maximum
	• 802.11a/g, 6Mbps: -86dBm maximum
	• 802.11a/g, 54Mbps: -72dBm maximum
	• 802.11n, MCS07: -67dBm maximum
	• 802.11n, MCS15: -64dBm maximum
	• 802.11ac, MCS0(VHT80): -84dBm maximum
	• 802.11ac, MCS9(VHT80): -59dBm maximum
	• 802.11ac, MCS9(VHT160): -58.5dBm maximum
	•802.11ax, MCS11(HE40): -57dBm maximum
	•802.11ax, MCS11(HE80): -54dBm maximum
	•802.11ax, MCS11(HE160): -53.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure
Antenna type	riigh efficiency afficinia with spatial diversity, mounted in the display efficiosare
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN
	MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm
Dillielizioliz	2. Type 1216: 1.67 x 12.0 x 16.0 mm
Maiah	
Weight	1. Type 2230: 2.8g
	2. Type 1216: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C)
	Non-operating: -40° to 176° F (-40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing)
	Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m)
	Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
HP Integrated Module with Blu	etooth 4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Card Technology
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Card Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	1 11 11
Muniver of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Bata a 155	
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels



	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW
	Peak (Rx): 230 mW
	Selective Suspend: 17 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826
	Low Voltage Directive IEC950
	UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance
	LE Link Layer Ping LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising
	LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 –Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)
	BT5.2
	ESR9/10 Compliance
	LE Advertisement Extensions
	Channel Selection Algo
	Limited High Duty Cycle Non-Connectable Advertising
	2Mbps LE
	LE Long Range

^{1.} Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.



^{2.} Check latest software/driver release for updates on supported security features.

^{3.} The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

^{4.} Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

	ax 2x2 Wi-Fi 6 + BT5.2 Wireless Card (802.11ax 2x2, supporting gigabit data rate) ¹
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi® certified modules
Frequency Band	802.11b/g/n/ax
,,	• 2.402 – 2.482 GHz
	802.11a/n/ac/ax
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: max 300Mbps
	• 802.11ac: max 866.7Mbps
	• 802.11ax: max 1201Mbps
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security ²	• IEEE and Wi-Fi® certified 64 / 128 bit WEP encryption for a/b/g mode only
,	AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	WPA3 certification
	• IEEE 802.11i
	• WAPI
Network Architecture Models	Ad-hoc (Peer to Peer)
	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power³	• 802.11b: +18.5dBm minimum
	• 802.11g: +17.5dBm minimum
	• 802.11a: +18.5dBm minimum
	• 802.11n HT20(2.4GHz): +15.5dBm minimum
	• 802.11n HT40(2.4GHz): +14.5dBm minimum
	• 802.11n HT20(5GHz): +15.5dBm minimum
	• 802.11n HT40(5GHz): +14.5dBm minimum
	• 802.11ac VHT80(5GHz): +11.5dBm minimum
	• 802.11ax HE40(2.4GHz): +10dBm minimum
	• 802.11ax HE80(5GHz): +10dBm minimum



<u> </u>	
Power Consumption	• Transmit mode:2.5 W
	Receive mode:2 W
	• Idle mode (PSP): 180 mW (WLAN Associated)
	Idle mode:50 mW (WLAN unassociated)
	Connected Standby/Modern Standby: 10mW
	Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management
	802.11 compliant power saving mode
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum
	802.11b, 11Mbps: -84dBm maximum
	802.11a/g, 6Mbps: -86dBm maximum
	802.11a/g, 54Mbps: -72dBm maximum
	802.11n, MCS07: -67dBm maximum
	802.11n, MCS15: -64dBm maximum
	802.11ac, MCSO: -84dBm maximum
	802.11ac, MCS9: -59dBm maximum
	•802.11ax, MCS11(HE40): -57dBm maximum
Automo turo	•802.11ax, MCS11(HE80): -54dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN
	MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm
Dillielisiolis	2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g
weight	2. Type 126: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C)
remperature	Non-operating: –40° to 176° F (–40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing)
	Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m)
Theread C	Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF;
	LED OFF – Radio ON
HP Integrated Module with Blue	etooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Card Technology
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1 /5.2 Wireless Card Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	
number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Datas and Throughout	
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5)
	or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum
	transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW
	Peak (Rx): 230 mW



	Selective Suspend: 17 mW
	Microsoft Windows Bluetooth Software
Bluetooth® Software Supported Link Topology	MICROSOFT WINDOWS BLUETOOTH SOFTWARE
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management	ETS 300 328, ETS 300 826
Certifications	Low Voltage Directive IEC950
	UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance
	LE Link Layer Ping
	LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising
	LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 –Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)
	BT5.1
	ESR9/10 Compliance
	LE Advertisement Extensions
	Channel Selection Algo
	Limited High Duty Cycle Non-Connectable Advertising
	2Mbps LE
	LE Long Range

^{1.} Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.



^{2.} Check latest software/driver release for updates on supported security features.

^{3.} The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

^{4.} Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

1x1) Wi-Fi 5 and Bluetooth® 4.2 Wireless Card¹
IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11d
IEEE 802.11e
IEEE 802.11h
IEEE 802.11i
IEEE 802.11k
IEEE 802.11r
IEEE 802.11v
Wi-Fi® certified modules
802.11b/g/n
• 2.402 – 2.482 GHz
802.11a/n/ac
• 4.9 – 4.95 GHz (Japan)
• 5.15 – 5.25 GHz
• 5.25 – 5.35 GHz
• 5.47 – 5.725 GHz
• 5.825 – 5.850 GHz
• 802.11b: 1, 2, 5.5, 11 Mbps
• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
• 802.11n: max 150Mbps
• 802.11ac: max 433.3Mbps
Direct Sequence Spread Spectrum
BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
• IEEE and Wi-Fi® certified 64 / 128 bit WEP encryption for a/b/g mode only
AES-CCMP: 128 bit in hardware
• 802.1x authentication
• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
WPA2 certification
WPA3 certification
• IEEE 802.11i
• WAPI
Ad-hoc (Peer to Peer)
Infrastructure (Access Point Required)
IEEE 802.11 compliant roaming between access points
• 802.11b: +14dBm minimum
• 802.11g: +12dBm minimum
• 802.11a: +12dBm minimum
• 802.11n HT20(2.4GHz): +12dBm minimum
• 802.11n HT40(2.4GHz): +12dBm minimum
• 802.11n HT40(2.4GHz): +12dBm minimum • 802.11n HT20(5GHz): +10dBm minimum
 802.11n HT40(2.4GHz): +12dBm minimum 802.11n HT20(5GHz): +10dBm minimum 802.11n HT40(5GHz): +10dBm minimum
• 802.11n HT40(2.4GHz): +12dBm minimum • 802.11n HT20(5GHz): +10dBm minimum



	Idle mode (PSP) 180 mW (WLAN Associated)
	• Idle mode 50 mW (WLAN unassociated)
	Connected Standby 10mW
	Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management
_	802.11 compliant power saving mode
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum
-	802.11b, 11Mbps: -84dBm maximum
	802.11a/g, 6Mbps: -86dBm maximum
	802.11a/g, 54Mbps: -72dBm maximum
	802.11n, MCS07: -67dBm maximum
	802.11n, MCS15: -64dBm maximum
	802.11ac, MCS0: -84dBm maximum
	802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna.
	One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN
	communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm
Weight	Type 2230: 2.8g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C)
	Non-operating: –40° to 176° F (–40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing)
	Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m)
100 0 11 11	Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF;
	LED OFF – Radio ON
	ooth 4.0/4.1/4.2 Wireless Card Technology
Bluetooth ^a Specification	4.0/4.1/4.2 Wireless Card Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)
	BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or
	864 kbps symmetric (3-EV5)
	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum
	transmit power of + 4 dBm for BR and EDR.
	Peak (Tx) 330 mW
	Peak (Rx) 230 mW
	Selective Suspend 17 mW
Transmit Power	USB 2.0 compliant
Power Consumption	Microsoft Windows Bluetooth Software
Bluetooth® Software Supported Lin	Microsoft Windows ACPI, and USB Bus Support
Topology	·
Power Management	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Certifications	4.0/4.1/4.2 Compliant
C. C. ICACIONS	They may be compliant



Power Management	ETS 300 328, ETS 300 826
Certifications	Low Voltage Directive IEC950
	UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance
	LE Link Layer Ping
	LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising
	LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 –Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)

^{1.} Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.



^{2.} Check latest software/driver release for updates on supported security features.

^{3.} The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

^{4.} Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Wireless LAN Standards	ax 2x2 Wi-Fi 6 + BT5.3 Wireless Card (802.11ax 2x2, supporting gigabit data rate) ¹ IEEE 802.11a
WIFELESS LAN STANDARDS	IEEE 802.11d IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n IEEE 802.11ac
	1 00-11140
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi® certified modules
Frequency Band	802.11b/g/n/ax
	• 2.402 – 2.482 GHz
	802.11a/n/ac/ax
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: max 300Mbps
	• 802.11ac: max 866.7Mbps
	• 802.11ax: max 1201Mbps
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security ²	• IEEE and Wi-Fi® certified 64 / 128 bit WEP encryption for a/b/g mode only
	AES-CCMP: 128 bit in hardware
	802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	WPA3 certification
	• IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	
	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power³	• 802.11b: +18.5dBm minimum
	• 802.11g: +17.5dBm minimum
	• 802.11a: +18.5dBm minimum
	• 802.11n HT20(2.4GHz): +15.5dBm minimum
	• 802.11n HT40(2.4GHz): +14.5dBm minimum
	• 802.11n HT20(5GHz): +15.5dBm minimum
	• 802.11n HT40(5GHz): +14.5dBm minimum
	• 802.11ac VHT80(5GHz): +11.5dBm minimum
	• 802.11ax HE40(2.4GHz): +10dBm minimum
	• 802.11ax HE80(5GHz): +10dBm minimum



Power Consumption	• Transmit mode:2.5 W	
rower consumption	• Receive mode: 2 W	
	• Idle mode (PSP) 180 mW (WLAN Associated)	
	• Idle mode:50 mW (WLAN unassociated)	
	Connected Standby/Modern Standby: 10mW	
	Radio disabled: 8 mW	
Power Management	ACPI and PCI Express compliant power management	
	802.11 compliant power saving mode	
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum	
•	802.11b, 11Mbps: -84dBm maximum	
	802.11a/g, 6Mbps: -86dBm maximum	
	802.11a/g, 54Mbps: -72dBm maximum	
	802.11n, MCS07: -67dBm maximum	
	802.11n, MCS15: -64dBm maximum	
	802.11ac, MCS0: -84dBm maximum	
	802.11ac, MCS9: -59dBm maximum	
	802.11ax, MCS11(HE40): -57dBm maximum	
	802.11ax, MCS11(HE80): -54dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure	
5.		
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN	
	MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm	
	2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8g	
	2. Type 126: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating: 14° to 158° F (–10° to 70° C)	
	Non-operating: –40° to 176° F (–40° to 80° C)	
Humidity	Operating: 10% to 90% (non-condensing)	
	Non-operating: 5% to 95% (non-condensing)	
Altitude	Operating: 0 to 10,000 ft (3,048 m)	
	Non-operating: 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF;	
	LED OFF – Radio ON	
HP Integrated Module with Blu	retooth 4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Card Technology	
Bluetooth [®] Specification	4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Card Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)	
	BLE: 0~39 (2 MHz/CH)	
Data Rates and Throughput		
	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps	
Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channe		
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power		
i raiismit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum	
	transmit power of + 4 dBm for BR and EDR.	
Power Consumption	Peak (Tx): 330 mW	
	Dools (Dy), 220 mW	
	Peak (Rx): 230 mW	



	Selective Suspend: 17 mW		
lectrical Interface	Microsoft Windows Bluetooth Software		
Bluetooth® Software Supported Link Topology	Microsoft Windows ACPI, and USB Bus Support		
Power Management	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Certifications	ETS 300 328, ETS 300 826		
	Low Voltage Directive IEC950		
	UL, CSA, and CE Mark Peak (Tx): 330 mW		
	Peak (Rx): 230 mW		
	Selective Suspend: 17 mW		
Power Management	Microsoft Windows Bluetooth Software		
Certifications			
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance		
• •	LE Link Layer Ping		
	LE Dual Mode		
	LE Link Layer		
	LE Low Duty Cycle Directed Advertising		
	LE L2CAP Connection Oriented Channels		
	Train Nudging & Interlaced Scan		
	BT4.2 ESR08 Compliance		
	LE Secure Connection- Basic/Full		
	LE Privacy 1.2 –Link Layer Privacy		
	LE Privacy 1.2 –Extended Scanner Filter Policies		
	LE Data Packet Length Extension		
	FAX Profile (FAX)		
	Basic Imaging Profile (BIP)2		
	Headset Profile (HSP)		
	Hands Free Profile (HFP)		
	Advanced Audio Distribution Profile (A2DP)		
	BT5.1		
	ESR9/10 Compliance		
	LE Advertisement Extensions		
	Channel Selection Algo		
	Limited High Duty Cycle Non-Connectable Advertising		
	2Mbps LE		
	LE Long Range		

^{1.} Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.



^{2.} Check latest software/driver release for updates on supported security features.

^{3.} The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

^{4.} Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Technical Specifications – Audio

INPUT/OUTPUT DEVICES

	ial)/128 Laser Mouse (China only	y)	
Dimensions (H x L x W)	112 x 63 x 36.2 mm (L x W x H)		
Weight	85 g		
Environmental	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
Electrical	Operating voltage	5 VDC, +/-5%	
	Power consumption (typical)	100mA	
	Resolution	1,200 DPI	
	Sensor	Optical/ Laser USB mouse sensor	
	Tracking speed	30 inch/sec (max)	
	Tracking acceleration	8G(max), 1G=9.8m/s2	
Mechanical	Connector	USB	
	Cable length	6 ft (1.8 m)	
	Color	Jack Black	
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC, EAC	

HP Wired Desktop 320M Mouse		
	Keys	Left/right key
Physical Characteristics	Dimensions(L x W x H)	4.09 x2.50 x 1.40 in (103.8x 63.4 x 35.5 mm)
	Weight	0.16 lb(72g)
	Operating voltage	5 VDC, +/-0.25V
	Power consumption	100 mA Max
Electrical	System interface	USB Port
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV (Class B)
	EMI - RFI	European Standard EN 55022: 2006+A1: 2007, Class B. FCC/CFR 47: Part 15 Class B
	Keycaps	0.3mm key travel
Mechanical	Key actuation	75±20g
	Key life	1million cycles
	Key structure type	Tact Switch



Technical Specifications – Audio

	Key-leveling mechanisms	N/A	N/A		
	Operating temperature	10° to 90° C			
	Non-operating temperature	-30° C to 95° C			
	Operating humidity	N/A			
	Non-operating humidity	10% to 90% (non-condensing at ambient)			
	Operating shock	N/A	N/A		
Environmental	inon-operating snock	i. Half-Sine Shock – End-Use Handling, Non-Operational Sample size: 5pcs. Condition: Sample power off. Axis: X, Y, Z axis (all 6 faces) – sample normal mode of operation. Number of shocks: 1 shock/face. Pulse duration: < 3 ms Velocity change: 50lps (inch-per-second)- 65lps desired. ii. Trapezoidal Shock- Transportation Environment, Non-Operational Sample size: 5pcs. Condition: Sample power off. Orientation: All six faces: Front, Rear, Left, Right, Bottom, and Top. Configuration: As intended for shipment Number of shocks: 1 shock/face. Minimum faired acceleration: 30G's. Test also at 40 and 50G's to find margin. Velocity change: 266lps (inch-per-second) for product mass (m) 20 <m<40lbs.< th=""></m<40lbs.<>			
	Operating vibration	Frequency (Hz)	Slope (dB/oct)	PSD (g²/Hz)	
		5-350	0	0.0001	
		350-500	-6	-	
		500	-	0.00005	
		(~0.21G _{nms})			
		T	otal Test time: 10 minute	S	
		Frequency (Hz)	Slope (dB/oct)	PSD (g²/Hz)	
		5.100	0	0.015	
				0.0.0	
	Non-operating vibration	100-137	-6	-	
	Non-operating vibration	100-137 137-350	-6 0	0.008	
	Non-operating vibration	100-137 137-350 350-500	-6	- 0.008 -	
		100-137 137-350 350-500 500	-6 0 -6	-	
	Non-operating vibration Drop (out of box)	100-137 137-350 350-500	-6 0 -6	- 0.008 -	
	Drop (out of box)	100-137 137-350 350-500 500	-6 0 -6	- 0.008 -	
Approvals	Drop (out of box)	100-137 137-350 350-500 500 76cm on carpet, six-drop N/A	-6 0 -6 -	- 0.008 -	



Technical Specifications – Audio

	ed SmartCard CCID Keyboard	104 105 100 layout (depending the control)	
Physical Characteristics	Keys	104, 105, 109 layout (depending upon country)	
	Dimensions (L x W x H)	17.34 x 5.68 x 0.78in (440.6 x 144.5 x 1.98 cm)	
	Weight	1.32 lb (598g)	
Electrical	Operating voltage	5 VDC, +/-5%	
	Power consumption	100mA (All LED on)	
	System interface	USB Type A plug connector	
	ESD	Contact Discharge: 8 KV Air Discharge: 12.5 KV	
	EMI - RFI	Conforms to FCC rules for a Class B computing device	
Mechanical	Keycaps	Low-profile design	
	Switch actuation	60±10g nominal peak force with tactile feedback	
	Switch life	10 million keystrokes (Life tester)	
	Switch type	Contamination-resistant switch membrane	
	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	6 ft (1.8 m)	
Environmental	Acoustics	43-dBA maximum sound pressure level	
	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence	
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence	
Approvals	CE Marking, TUV, EAC, FCC, cUL	us/CSAus, ICES, RCM, VCCI, KCC, BSMI	
Ergonomic compliance	ISO 9241-4, TUVGS		



Technical Specifications – Audio

HP 125 (Antimicrobial) Wi	red Keyboard (China only)		
Physical Characteristics	Keys	104/105/107/109layout (depending upon country)	
	Dimensions (L x W x H)	436 x 138 x24.7 mm	
	Weight	471g	
Electrical	Operating voltage	5V +- 5%	
	Power consumption	50mA	
	System interface	USB Type A plug connector	
	ESD	Contact Discharge: 8 KV Air Discharge: 12.5 KV	
	EMI - RFI	Conforms to FCC rules for a Class B computing device	
Mechanical	Keycaps	Low-profile design	
	Switch actuation	55±10g nominal peak force with tactile feedback	
	Switch life	10 million keystrokes (Life tester)	
	Switch type	Contamination-resistant switch membrane	
	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	1.8 m	
Environmental	Acoustics	43-dBA maximum sound pressure level	
	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-4° to 149° F (-20° to 65° C)	
	Operating humidity	10% to 95% (non-condensing at ambient)	
	Non-operating humidity	0% to 95% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence	
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence	
Approvals	UL, cUL, FCC, CE, TUV GS, VCCI,	BSMI, RCM, KCC, USB-IF, WHQL, EN/IEC 60601-1	
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and TUVGS		



Technical Specifications – Audio

AUDIO/MULTIMEDIA

Type Integrated

HD Stereo Codec Realtek ALC3252

Audio I/O Ports Front: Headset connector supports a CTIA and OMTP style headset and is retaskable as a Line-in,

Line-out, Microphone-in or Headphone-out port

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

externally

Multi-streaming Capable Playback multi-streaming allows independent audio

streams to be sent to/from the front jacks and integrated speaker.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes

Technical Specifications – Power

POWER SUPPLY

Operating Voltage Range 90Vac~264Vac **Rated Voltage Range** 100Vac~240Vac **Rated Line Frequency** 50Hz~60Hz **Operating Line Frequency** 47Hz~63Hz **Rated Input Current with** 65W≤ 1.6A

Energy Efficient* Power

Supply

DC Output +19.5V

Current Leakage (NFPA 99:

2102)

Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or

that contact patients in normal use. Per section 10.3.5.1.

Average efficiency 88% at 115V

Average efficiency 89% at 230V

Less than 100 microamps of leakage current at 264 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care

facility or that contact patients in normal use. Per section 10.3.5.1.

Power cord length 6.0 ft. (1.83 m)

Dimensions 90 x 51 x 28.5mm & 102 x 55 x 30mm



Technical Specifications – Weights and Dimensions

WEIGHT AND DIMENSIONS¹

System

Dimensions 6.97 x 6.89 x 1.35 in 177 x 175 x 34.2 mm

Weight² 2.74 lb

1.25 kg

Volume 64 cu in

1.05 L

Packaging dimensions and weight

Dimensions 19.57 x 5.04 x 8.78 in

497 x 128 x 223 mm

MPP/EPE: 19.61 x 9.25 x 5.20 in

498 x 235 x 132 mm

Weight 7.36 lb

3.34 kg

MPP/EPE: 6.4 lb 2.9 kg

Palletization and Container

Pallet Profile 1 unit/carton

18 cartons/layer

5~6 layers per pallet max depending on details of air freight 90~108 units per pallet depending on details of air freight

MPP/EPE: 1 unit/carton 10 cartons/layer

10~19 layers per pallet max depending on details of ground/sea freight 100~190 units per pallet depending on details of ground/sea freight

Pallet Size Loaded 45.354 x 39.13 x 57.80 in

1152 x 994 x 1468 mm

MPP/EPE: 46.26 x 39.21 x 103.74 in 1175 x 996 x 2635 mm

- 1. Packaging material used will vary by country
- 2. Configured with 1 SATA Drive



After-Market Options (availability may vary by region)

<u>Type</u>	<u>Description</u>	<u>Part Number</u>
Graphics Solutions	HP HDMI Standard Cable Kit	T6F94AA
	HP DisplayPort™ To HDMI True 4k Adapter	2JA63AA
	HP DisplayPort™ Cable Kit	VN567AA
	HP DisplayPort™ To VGA Adapter	AS615AA
	HP DisplayPort™ To DVI-D Adapter	FH973AA
Desktop Mini Accessories	HP Desktop Mini 2.5" SATA Drive Bay kit v2	13L70AA
	HP Desktop Mini LockBox V2	3EJ57AA
	HP Desktop Mini DVD-Writer ODD Expansion Module	K9Q83AA
	HP Desktop Mini I/O Expansion Module	K9Q84AA
	HP Desktop Mini Security/Dual VESA Sleeve v3	13L67AA
	HP Desktop Mini Security/Dual VESA Sleeve v3 With Power Supply Holder	13L68AA
	HP B300 PC Mounting Bracket with Power Supply Holder	7DB37AA
	HP Desktop Mini Vertical Chassis Stand	G1K23AA
	HP DM Power Supply Holder Kit v2	7DB38AA
	HP Desktop Mini Port Cover v3	13L69AA
	HP Integrated Work Center Stand 5	G1V61AA
Data Storage Drives	HP PCIe NVME TLC 256GB SSD M.2 Drive	1CA51AA
	HP PCIe NVME TLC 512GB SSD M.2 Drive	X8U75AA
Input Devices	HP Wired Desktop 320K Keyboard	9SR37AA
	HP USB Business Slim SmartCard CCID Keyboard	Z9H48AA
	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
	HP Wired Desktop 320M Mouse	9VA80AA
	HP 125 Wired Keyboard	266C9AA
	HP 125 Wired Mouse	265A9AA
	HP 128 Laser Wired Mouse	265D9AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 225 Antimicrobial Wired Mouse and Keyboard Combo (China Only)	286K3AA
Multimedia Devices	HP S101 Speaker Bar	5UU40AA
	HP Stereo 3.5mm Headset G2	428K7AA
	HP Stereo USB Headset G2	428K6AA
	HyperX Cloud MIX – Gaming Headset (Black-Gunmetal)	4P5K9AA
	HyperX Cloud Flight – Wireless Gaming Headset (Black-Red)	4P5L4AA



After-Market Options (availability may vary by region)

	HyperX Cloud Stinger Core – Gaming Headset (Black)	4P4F4AA
	Inspers cloud stillger core = darling fleadset (black)	4541444
	HyperX Cloud Core + 7.1 Gaming Headset (Black)	4P4F2AA
	HyperX SoloCast USB WHT Microphone (Black)	4P5P8AA
Security Devices	HP Dual Head Keyed Cable Lock	T1A64AA
	HP Keyed Cable Lock 10mm	T1A62AA
	HP Master Keyed Cable Lock 10mm	T1A63AA
Stands and Mounting		
Accessories	HP B250 PC Mounting Bracket	8RA46AA
	HP B300 PC Mounting Bracket	2DW53AA
	HP B500 PC Mounting Bracket	2DW52AA
	HP Quick Release Bracket 2	6KD15AA



Change Log

© Copyright 2023 HP Development Company, L.P.

The information contained herein is subject to change without notice. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

Microsoft and Windows are registered trademarks or trademarks of Microsoft Corporation in the U.S. and/or other countries. Intel, Celeron®, Core, Pentium are registered trademarks or trademarks of Intel Corporation in the U.S. and/or other countries. Bluetooth is a trademark of its proprietor, used by HP Inc. under license. NVIDIA, GeForce, Kepler and NVS are trademarks and/or registered trademarks of NVIDIA Corporation in the U.S. and other countries. AMD and Radeon are trademarks of Advanced Micro Devices, Inc. ENERGY STAR is a registered trademark owned by the U.S. Environmental Protection Agency.

DisplayPort[™] and the DisplayPort[™] logo are trademarks owned by the Video Electronics Standards Association (VESA®) in the United States and other countries. Wi-Fi® is a registered trademark of Wi-Fi Alliance®.

Date of change:	Version History:		Description of change:
June 9, 2022	From v1 to v2	Update	Environmental table certifications updated
December 9, 2022	From v2 to v3	Update	Operating system updated
March 9, 2023	From v3 to v4	Addition	"Wireless Card" Added to Wireless Card in the end of module
			description in Networking and communication section
March 28, 2023	From v4 to v5	Removal	Dual Type-A Hi-Speed USB 480Mbps signaling rate port removed from
			flex card 2 in call outs section back image.
May 11, 2023	From v5 to v6	Addition	HDD disclaimer added in both Storage sections
August 29, 2023	From v6 to v7	Correction	Packaging Weight corrected
October 30, 2023	From v7 to v8	Update	Security section updated
November 1, 2023	From v8 to v9	Removal	"Shipped with Windows 10" removed

